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| Customer Approved |
| |
| Date: |

Part No.:
LL810IR1C-A01T4

DATA SHEET

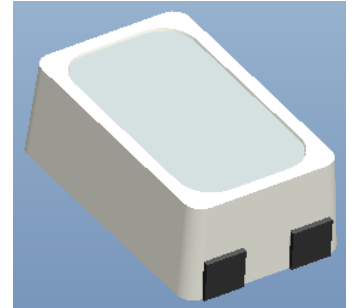
Issue Date: 2019.04.10
Issue No.: LTD-810IR-001
REVISION: V1

| Designer | Checker | Approver |
|-------------|-------------|--------------|
| <i>Lisa</i> | <i>Rock</i> | <i>Allen</i> |

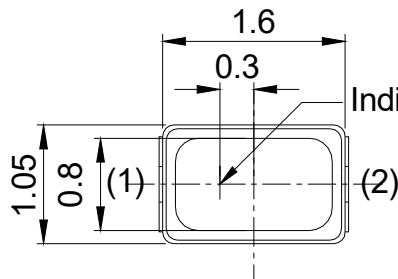
Infrared LED Type ■ Top view 1016 Package LL810IR1C-A01T4

Features

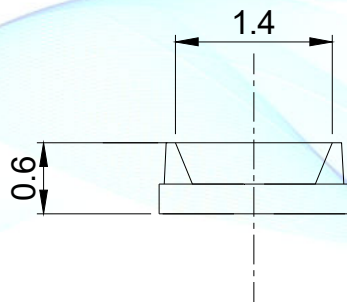
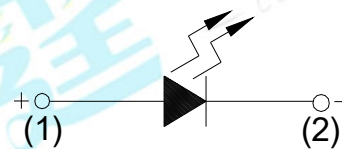
- 1016 package
- Top view LED
- Compatible with infrared and vapor phase reflow solder process
- Pb-free
- RoHS compliant



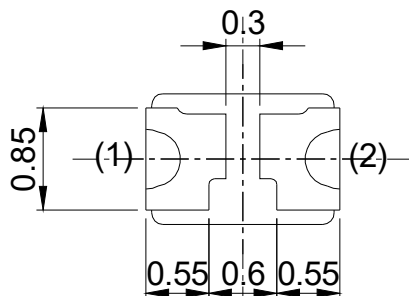
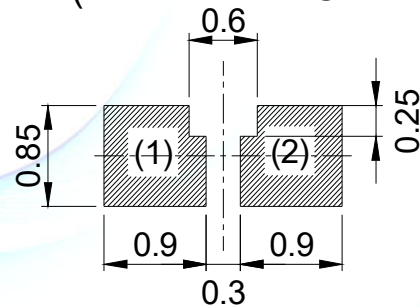
Package Dimensions



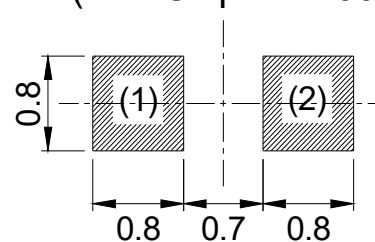
Polarity



Recommended Solder Pad
(Be The First Choice)



Recommended Solder Pad
(For Chip LED 0603)



Note:

Tolerance unless mentioned is ± 0.1 mm, Unit = mm.

Applications

- Free air transmission system
- Infrared remote control units with high power requirement
- Smoke detector
- Infrared applied system

Device Selection Guide

| Emitted Color | Resin Color |
|---------------|-------------|
| Infrared | Water Clear |

Absolute Maximum Ratings (T_{Soldering}=25°C)

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|------------------|---------------------------------------------------------------------------|------|
| Forward Current | I _F | 150 | mA |
| Peak Forward Current (Duty 1/10 @1ms) | I _{FP} | 500 | mA |
| Power Dissipation | P _d | 220 | mW |
| Operating Temperature | T _{opr} | -40 ~ +85 | °C |
| Storage Temperature | T _{stg} | -40 ~ +100 | °C |
| Soldering Temperature | T _{sol} | Reflow Soldering : 260°C for 10 sec. Hand Soldering : 350°C for 3 sec. | |
| Reverse Voltage | V _R | 5 | V |

Note:

The products are sensitive to static electricity and must be carefully taken when handling products.

Electro-Optical Characteristics (T_{Soldering}=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Condition |
|-------------------|-------------------|------|------|------|-------|----------------------|
| Radiant Intensity | E _e | 1.5 | 2.6 | 4 | mw/sr | I _F =20mA |
| Peak Wavelength | λ _P | --- | 940 | --- | nm | I _F =20mA |
| Forward Voltage | V _F | 1.1 | --- | 1.7 | V | I _F =20mA |
| Viewing Angle | 2θ _{1/2} | --- | 120 | --- | deg | I _F =20mA |
| Reverse Current | I _R | --- | --- | 10 | μA | V _R =5V |

Notes:

- 1.Tolerance of Radiant Intensity ±10%..
- 2.Tolerance of Forward Voltage : ±0.1V.

Bin Code Description

Bin Range of Radiant Intensity

| Bin Code | Min. | Max. | Unit | Condition |
|----------|------|------|-------|----------------------|
| A1 | 1.5 | 2 | mw/sr | I _F =20mA |
| A2 | 2 | 3 | | |
| A3 | 3 | 4 | | |

Bin Range of Forward Voltage

| Bin Code | Min. | Max. | Unit | Condition |
|----------|------|------|------|----------------------|
| V1 | 1.1 | 1.3 | V | I _F =20mA |
| V2 | 1.3 | 1.5 | | |
| V3 | 1.5 | 1.7 | | |

Notes:

- 1.Tolerance of Luminous Intensity ±10%.
- 2.Tolerance of Forward Voltage : ±0.1V.

Typical Electro-Optical Characteristics Curves

Fig.1-Forward Current vs. Forward Voltage $T_a=25^\circ\text{C}$

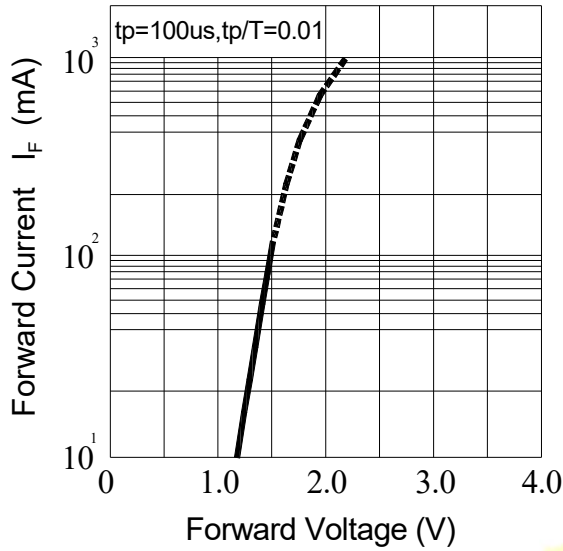


Fig.2-Relative Intensity vs. Forward Current

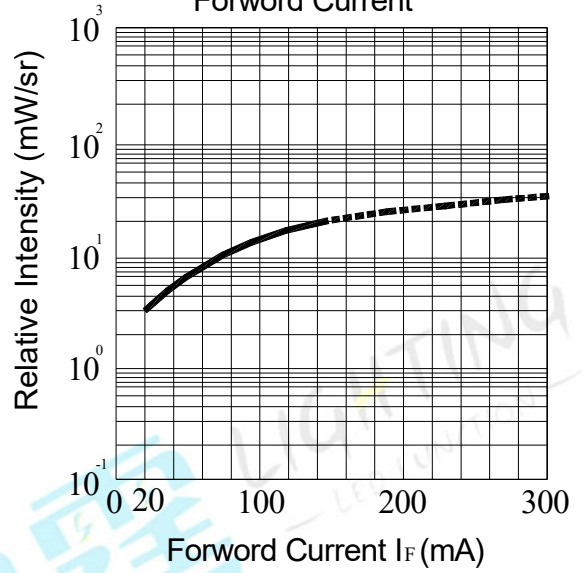


Fig.3-Forward Current vs. Ambient Temperature

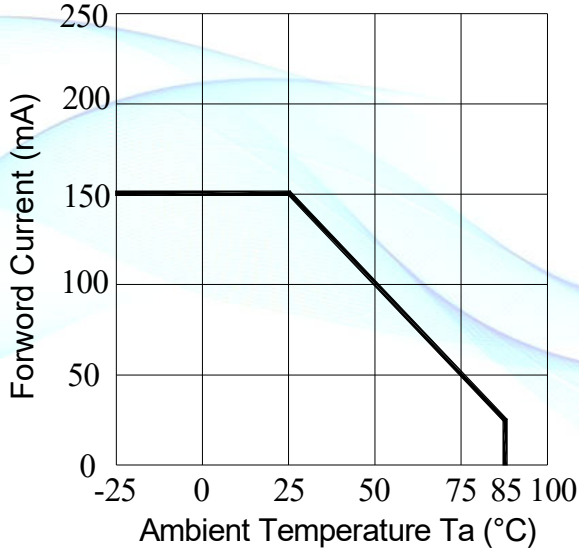
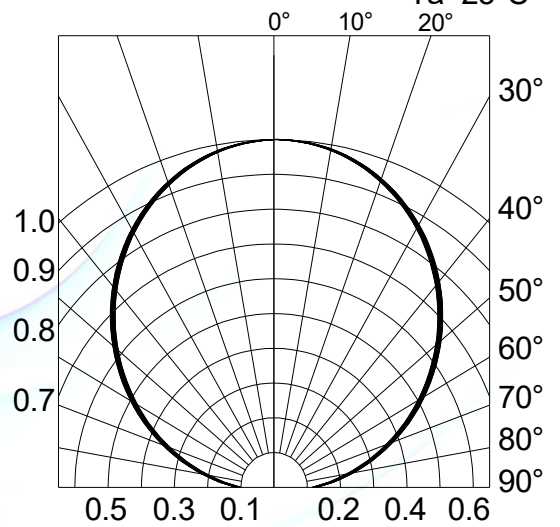


Fig.4-Radiation Diagram $T_a=25^\circ\text{C}$



Typical Electro-Optical Characteristics Curves

Fig.5-Forward Voltage Shift vs. Junction Temperature

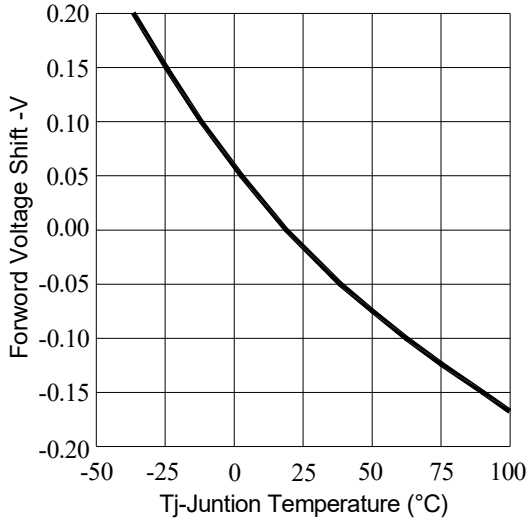
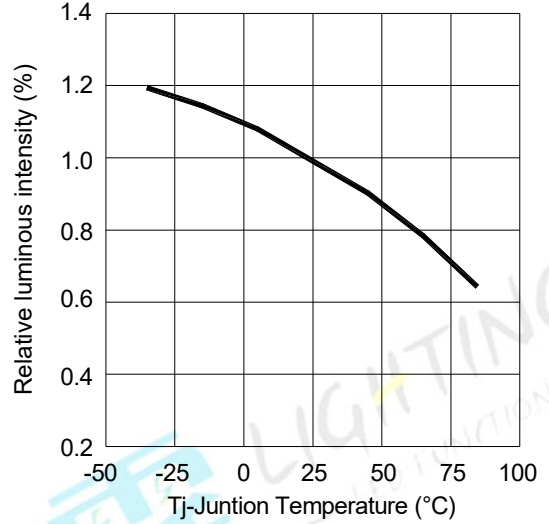
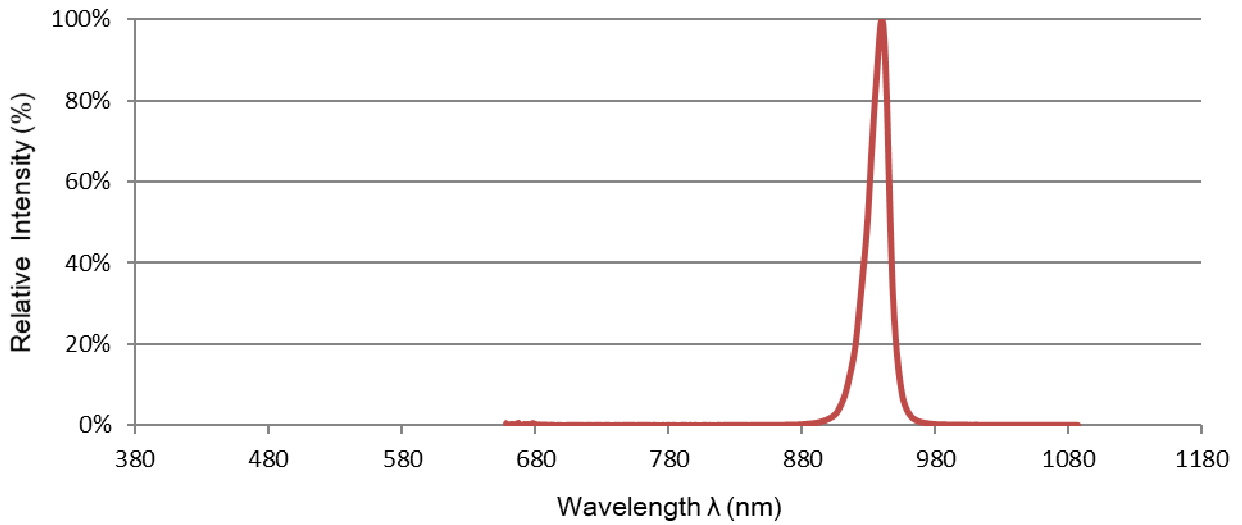


Fig.6-Relative Luminous Intensity vs. Junction Temperature



Spectrum Distribution



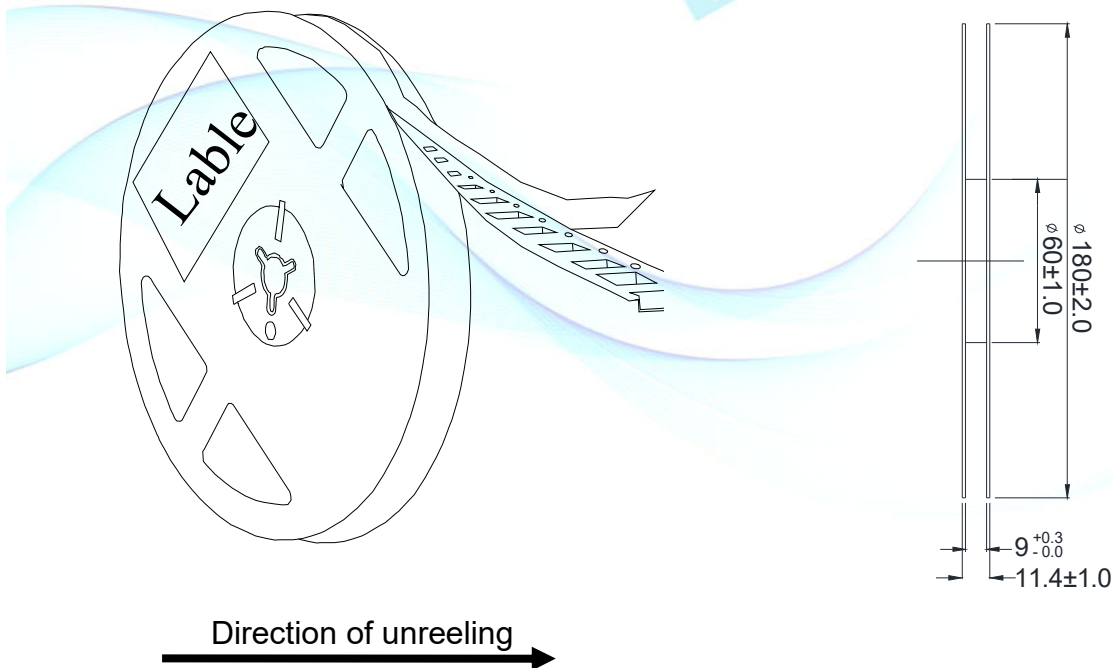
Moisture Resistant Packing Materials

Label Explanation



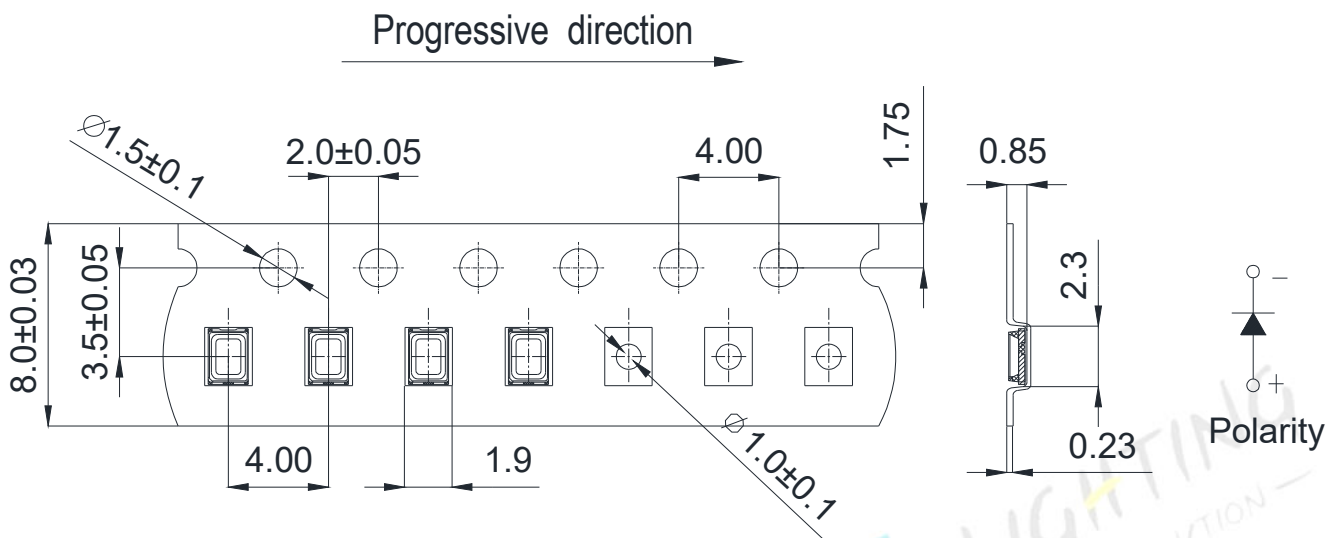
- QR code:
Contains all of the following information
- P/N: Product Number
- TYPE :Part NO.
- IV: Luminous Intensity Rank
- WD: Wavelength Rank
- VF: Forward Voltage Rank
- QTY: Packing Quantity
- LOT NO.: Lot Number

Taping method: Loaded Quantity 4,000 pcs Per Reel



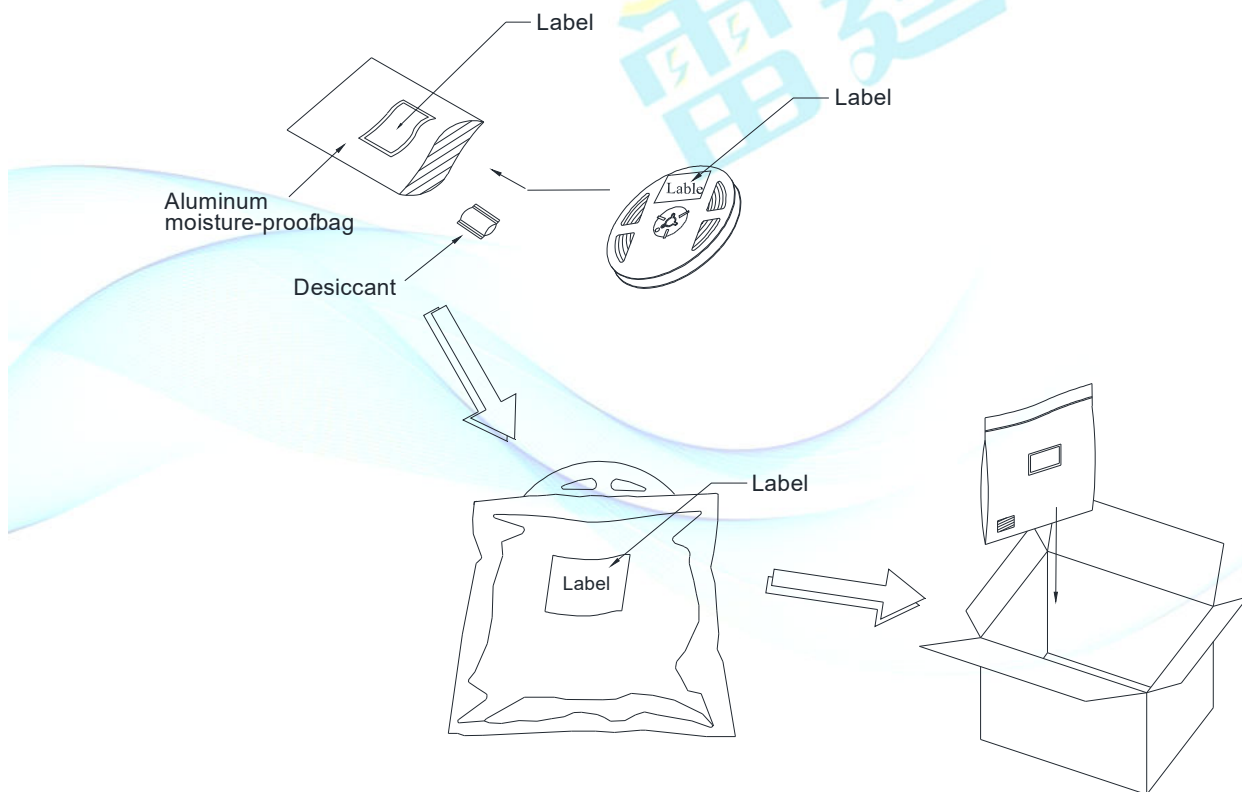
- Notes:
1. Tolerance unless mentioned is ± 0.1 mm, Unit = mm.
 2. Minimum packing amount is 1000 pcs per reel.

Carrier Tape Dimensions:



Note:
Tolerance unless mentioned is ± 0.1 mm, Unit = mm.

Moisture Resistant Packing Process



Moisture/Reflow sensitivity classification
IPC / JEDEC J-STD-020C: Level 3

Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

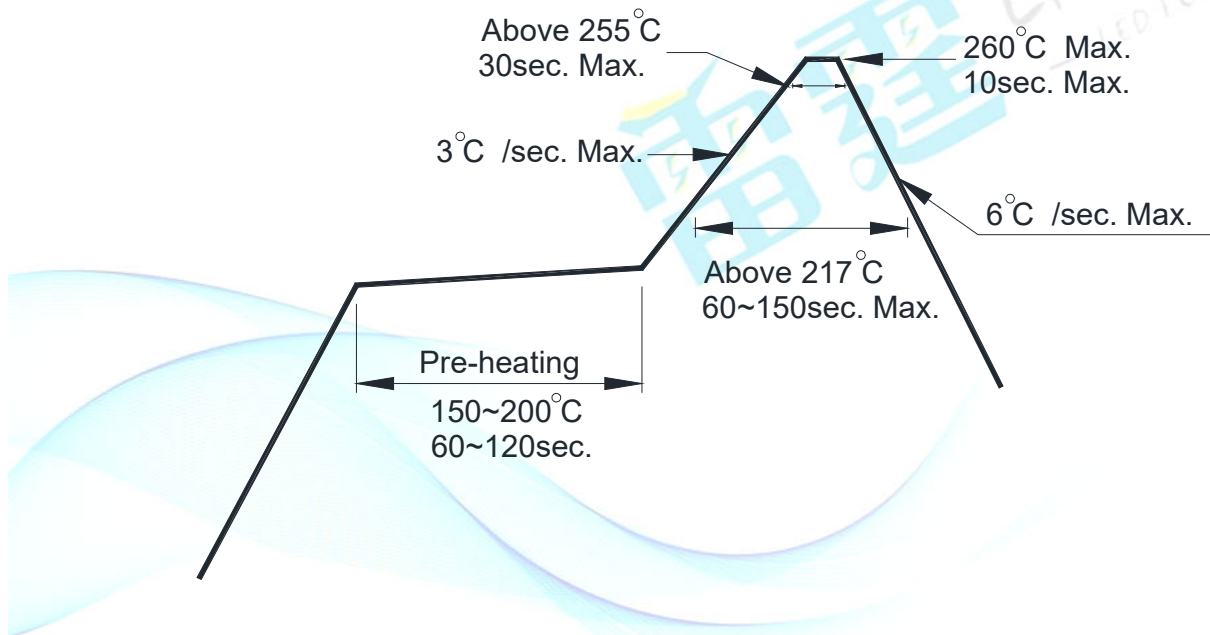
LTPD : 10%

| No. | Items | Test Condition | Test Hours/Cycles | Sample Size | Ac/Re |
|-----|-----------------------------------|------------------------------------------------|-------------------|-------------|-------|
| 1 | Reflow Soldering | Temp.: 260°C/10sec. | 6 Min. | 22 PCS. | 0/1 |
| 2 | Thermal Shock | H : +100°C/5min ∫ 10 sec L : -10°C/5min | 300 Cycles | 22 PCS. | 0/1 |
| 3 | Temperature Cycle | H : +100°C/15min ∫ 5 min L : -40°C/15min | 300 Cycles | 22 PCS. | 0/1 |
| 4 | High Temperature/Humidity Storage | Ta=85°C,85%RH | 1000 Hrs. | 22 PCS. | 0/1 |
| 5 | Low Temperature Storage | Ta=-40°C | 1000 Hrs. | 22 PCS. | 0/1 |
| 6 | High Temperature Storage | Ta=100°C | 1000 Hrs. | 22 PCS. | 0/1 |
| 7 | DC Operation Life | Ta=25°C, I _F = 20 mA | 1000 Hrs. | 22 PCS. | 0/1 |

Precautions for Use

1. Over-current-proof
Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).
2. Storage
 - 2.1 Do not open moisture proof bag before the products are ready to use.
 - 2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.
 - 2.3 After opening the package: The LED's floor life is 168H under 30°C or less and 60%RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
 - 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment: 60±5°C for 24 hours.

3. Soldering Condition
 - 3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.
4. Soldering Iron
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.
5. Repairing
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing